



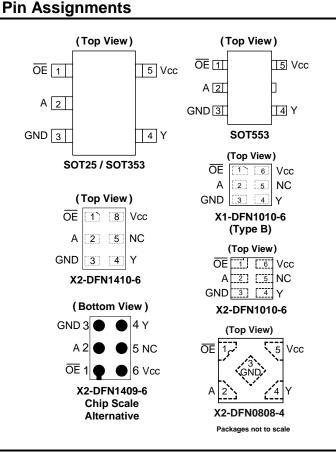
74LVC1G125

Description

The 74LVC1G125 is a single, non-inverting buffer/bus driver with a 3-state output. The output enters a high-impedance state when a HIGH-level is applied to the output enable $\overline{(OE)}$ pin. The device is designed for operation with a power supply range of 1.65V to 5.5V. The inputs are tolerant to 5.5V, allowing this device to be used in a mixed voltage environment. The device is fully specified for partial power down applications using I_{OFF}. The I_{OFF} circuitry disables the output preventing damaging current backflow when the device is powered down.

Features

- Wide Supply Voltage Range from 1.65 to 5.5V
- ± 24mA Output Drive at 3.3V
- CMOS Low Power Consumption
- I_{OFF} Supports Partial-Power-Down Mode Operation
- Inputs Accept Up to 5.5V
- ESD Protection Tested per JESD 22
 - Exceeds 200-V Machine Model (A115)
 - Exceeds 2000-V Human Body Model (A114)
 - Exceeds 1000-V Charged Device Model (C101)
- Latch-Up Exceeds 100mA per JESD 78, Class I
- Range of Package Options
- Direct Interface with TTL Levels
- Totally Lead-Free & Fully RoHS Compliant (Notes 1 & 2)
- Halogen and Antimony Free. "Green" Device (Note 3)



SINGLE BUFFER GATE WITH 3-STATE OUTPUT

Applications

- Voltage Level Shifting
- General Purpose Logic
- Power Down Signal Isolation
- Wide Array of Products Such as:
 - PCs, Networking, Notebooks, Netbooks, PDAs
 - Tablet Computers, E-readers
 - Computer Peripherals, Hard Drives, CD/DVD ROMs
 - TVs, DVDs, DVRs, Set Top Boxes
 - Cell Phones, Personal Navigation / GPS
 - MP3 Players, Cameras, Video Recorders

Notes:

- 1. No purposely added lead. Fully EU Directive 2002/95/EC (RoHS) & 2011/65/EU (RoHS 2) compliant.
- 2. See http://www.diodes.com/quality/lead_free.html for more information about Diodes Incorporated's definitions of Halogen- and Antimony-free, "Green" and Lead-free.
- 3. Halogen- and Antimony-free "Green" products are defined as those which contain <900ppm bromine, <900ppm chlorine (<1500ppm total Br + Cl) and <1000ppm antimony compounds.



Ordering Information (Note 4)

Г			<u>74 LVC1G</u> 1	25 XXX -7		1
Logic D	evice		Function	Package	Р	acking
Logic Device 74 : Logic Prefix LVC : 1.65 to 5.5 V Logic Family 1G : One Gate		125:	3-State Buffer OE active low		08-4 10-6 (Туре В) 10-6 409-6	ape & Reel
Part Number	Package	Р	ackage	Package	7" Tape	and Reel
	Code	(No	otes 5 & 6)	Size	Quantity	Part Number Suffix
74LVC1G125W5-7	W5	:	SOT25	3.0mm x 2.8mm x 1.2mm	3,000/Tape & Reel	-7

		· · · ·			
74LVC1G125W5-7	W5	SOT25	3.0mm x 2.8mm x 1.2mm 0.95mm lead pitch	3,000/Tape & Reel	-7
74LVC1G125SE-7	SE	SOT353	2.0mm x 2.0mm x 1.1mm 0.65mm lead pitch	3,000/Tape & Reel	-7
74LVC1G125Z-7	Z	SOT553	1.6mm x 1.6 mm x 0.62mm 0.5mm lead pitch	4,000/Tape & Reel	-7
74LVC1G125FS3-7	FS3	X2-DFN0808-4	0.8mm x 0.8 mm x 0.35mm 0.5mm pad pitch (diamond)	5,000/Tape & Reel	-7
74LVC1G125FW5-7	FW5	X1-DFN1010-6 (Type B)	1.0mm x 1.0mm x 0.5mm 0.35mm pad pitch	5,000/Tape & Reel	-7
74LVC1G125FW4-7	FW4	X2-DFN1010-6	1.0mm x 1.0mm x 0.4mm 0.35mm pad pitch	5,000/Tape & Reel	-7
74LVC1G125FX4-7	FX4	X2-DFN1409-6 (Chip scale alternative)	1.4mm x 0.9mm x 0.4mm 0.5mm pad pitch	5,000/Tape & Reel	-7
74LVC1G125FZ4-7	FZ4	X2-DFN1410-6	1.4mm x 1.0mm x 0.4mm 5,000/Tape & Reel 0.5mm pad pitch 5,000/Tape & Reel		-7

4. For packaging details, go to our website at http://www.diodes.com/products/packages.html.

Pad layout as shown on Diodes Inc. suggested pad layout which can be found on our website at http://www.diodes.com/package-outlines.html.
The taping orientation is located on our website at http://www.diodes.com/datasheets/ap02007.pdf.

Pin Descriptions

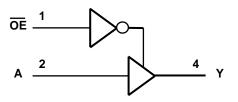
Notes:

Pin Name	Description
ŌĒ	Output Enable
A	Data Input
GND	Ground
Y	Data Output
V _{CC}	Supply Voltage
NC	No Connection

Function Table

Inp	Output	
OE A		Y
L	Н	
L	L L	
Н	Х	Z

Logic Diagram





Absolute Maximum Ratings (Notes 7 & 8) (@T_A = +25°C, unless otherwise specified.)

Symbol	Description	Rating	Unit
ESD HBM	Human Body Model ESD Protection	2	kV
ESD CDM	Charged Device Model ESD Protection	1	kV
ESD MM	Machine Model ESD Protection	200	V
Vcc	Supply Voltage Range	-0.5 to 6.5	V
VI	Input Voltage Range	-0.5 to 6.5	V
Vo	Voltage Applied to Output in High Impedance or IOFF State	-0.5 to 6.5	V
Vo	Voltage Applied to Output in High or Low State.	-0.5 to V _{CC} +0.5	V
I _{IK}	Input Clamp Current V _I < 0	-50	mA
Ι _{ΟΚ}	Output Clamp Current	-50	mA
lo	Continuous Output Current	±50	mA
I _{CC,} I _{GN}	Continuous Current Through V _{CC} or GND	±100	mA
TJ	Operating Junction Temperature	-40 to +150	°C
T _{STG}	Storage Temperature	-65 to +150	°C

Notes: 7. Stresses beyond the absolute maximum may result in immediate failure or reduced reliability. These are stress values and device

operation should be within recommend values. 8. Forcing the maximum allowed voltage could cause a condition exceeding the maximum current or conversely forcing the maximum current could cause a condition exceeding the maximum voltage. The ratings of both current and voltage must be maintained within the controlled range.

Recommended Operating Conditions (Note 9) (@T_A = +25°C, unless otherwise specified.)

Symbol		Parameter	Min	Max	Unit	
Ma a	Operating Voltage	Operating	1.65	5.5	V	
Vcc	Operating voltage	Data Retention Only	1.5	—	V	
		V _{CC} = 1.65V to 1.95V	$0.65 \times V_{CC}$	—		
VIH	High Lovel Input Veltage	$V_{CC} = 2.3V$ to 2.7V	1.7	—	v	
VIH	High-Level Input Voltage	$V_{CC} = 3V$ to 3.6V	2	—	v	
		V _{CC} = 4.5V to 5.5V	0.7 x V _{CC}	—		
		V _{CC} = 1.65V to 1.95V	—	0.35 x V _{CC}		
N/		V _{CC} = 2.3V to 2.7V	—	0.7	V	
VIL	Low-Level Input voltage	V _{CC} = 3V to 3.6V	—	0.8	v	
		V _{CC} = 4.5V to 5.5V	—	0.3 x V _{CC}		
VI	Input Voltage		0	5.5	V	
Vo	Output Voltage		0	Vcc	V	
		V _{CC} = 1.65V	_	-4		
	High-Level Output Current	$V_{CC} = 2.3V$	_	-8		
		V _{CC} = 2.7V	_	-12	~^^	
IOH			_	-16	mA	
		V _{CC} = 3V	—	-24		
		$V_{CC} = 4.5V$	—	-32		
		$V_{CC} = 1.65 V$	_	4		
		$V_{CC} = 2.3 V$	_	8		
IOL	Low-Level Output Current	V _{CC} = 2.7V	—	12	mA	
IOL		V _{CC} = 3V	—	16		
		vcc = 5v		24]	
		$V_{CC} = 4.5V$		32		
		$V_{CC} = 1.8V \pm 0.15V, 2.5V \pm 0.2V$	—	20		
Δt/ΔV	Input Transition Rise or Fall Rate	$V_{CC} = 3.3V \pm 0.3V$	—	10	ns/V	
		$V_{CC} = 5V \pm 0.5V$	—	5		
TA	Operating Free-Air Temperature		-40	+125	°C	

Note: 9. Unused inputs should be held at $V_{\mbox{CC}}\,\mbox{or Ground}.$



Electrical Characteristics (All typical values are at $V_{CC} = 3.3V$, $T_A = +25^{\circ}C$)

Symbol	Parameter	Test Conditions	N/	-4	40°C to +85°	С	-40°C to	+125°C	Unit	
Symbol	Parameter	Test Conditions	V _{cc}	Min	Тур	Max	Min	Max	Unit	
		I _{OH} = -100μA	1.65V to 5.5V	V _{CC} -0.1	_	_	$V_{CC} - 0.1$			
		I _{OH} = -4mA	1.65V	1.2	—	—	0.95			
		I _{OH} = -8mA	2.3V	1.9	_	_	1.7			
Vон	High-Level Output Voltage	I _{OH} = -12mA	2.7V	2.2	—	—	1.9		V	
	o alp at 1 on ago	I _{OH} = -16mA	3V	2.4	_	_	2.2			
		I _{OH} = -24mA	37	2.3	—	—	2.0	_		
		I _{OH} = -32mA	4.5V	3.8	—	—	3.4	_		
		I _{OL} = 100μA	1.65V to 5.5V	_	—	0.1	—	0.1		
		I _{OL} = 4mA	1.65V	—	—	0.45	—	0.7		
	Low-Level Output Voltage	I _{OL} = 8mA	2.3V	—	—	0.3	—	0.45		
V _{OL}		$I_{OL} = 12mA$	2.7V	—	—	0.4	—	0.6	V	
		I _{OL} = 16mA	3V	—	—	0.4	—	0.6		
		$I_{OL} = 24mA$	3V	—	—	0.55	—	0.8		
		I _{OL} = 32mA	4.5V	_	_	0.55	—	.8		
I	Input Current	V _I = 5.5 V or GND	0 to 5.5V	_	± 0.1	±5	—	± 100	μA	
I _{OFF}	Power Down Leakage Current	$V_{I} \text{ or } V_{O} = 5.5 V$	٥V	_	—	±10	_	±200	μA	
I _{OZ}	Z State Leakage Current	V _O =0 to 5.5V	3.6V		0.1	10		20	μA	
I _{CC}	Supply Current	V _I = 5.5V or GND I _O =0	5.5V	_	0.1	10	_	200	μA	
ΔI _{CC}	Additional Supply Current	Input at V _{CC} –0.6V	3V to 5.5V	_	_	500	—	5,000	μA	
Ci	Input Capacitance	$V_i = V_{CC} - or GND$	3.3V	—	5	—	—	—	pF	

Package Characteristics (All typical values are at V_{CC} = 3.3V, T_A = +25°C)

Symbol	Parameter	Test Conditions	V _{cc}	Min	Тур	Max	Unit
		SOT25		—	204	_	
		SOT353		_	371	_	
		SOT553		_	231	_	
0	Thermal Resistance	X2-DFN0808-4	$(N_{1}) = (10)$	_	400	_	°C/W
θ _{JA}	Junction-to-Ambient	X1-DFN1010-6 (Type B)	(Note 10)	_	435	—	°C/vv
		X2-DFN1010-6		_	445	_	
		X2-DFN1409-6		_	470	_	
		X2-DFN1410-6		_	460	_	
		SOT25		_	52	_	
		SOT353		_	143	_	
		SOT553		_	105	_	
0	Thermal Resistance	X2-DFN0808-4	(N_{1})	—	225	_	°C/W
θις	Junction-to-Case	X1-DFN1010-6 (Type B)	(Note 10)	_	250	_	
		X2-DFN1010-6			250	—	
		X2-DFN1409-6			275	_	
		X2-DFN1410-6			265	—	

Note: 10. Test condition for each of the eight package types: Device mounted on FR-4 substrate PC board, 2oz copper, with minimum recommended pad layout.



Switching Characteristics

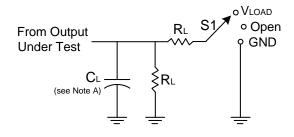
Parameter	From	То	Mar	TA	= -40°C to +85	5°C	T _A = -40°C	Uni	
Farameter	Input	Output	V _{CC}	Min	Тур	Max	Min	Max	_ 011
			1.8V ± 0.15V	1.0	3.3	8.0	1.0	10.5	
			2.5V ± 0.2V	0.5	2.2	5.5	0.5	7.0	
t _{pd}	А	Y	2.7V	0.5	2.5	5.5	0.5	7.5	ns
-			3.3V ± 0.3V	0.5	2.1	4.5	0.5	6.0	7
			5.0V ± 0.5V	0.5	1.7	4.0	0.5	5.5	
		DE Y	1.8 V ± 0.15V	1.0	4.1	9.4	1.0	12.0	
			2.5V ± 0.2V	0.5	2.8	6.6	0.5	8.5	
t _{en}	ŌĒ		2.7V	0.5	3.3	6.6	0.5	8.5	ns
				3.3V ± 0.3V	0.5	2.4	5.3	0.5	7.0
			5.0V ± 0.5V	0.5	2.1	5.0	0.5	6.5	
			1.8V ± 0.15V	1.0	4.3	9.2	1.0	12.0	
t _{dis} <u>OE</u>			2.5V ± 0.2V	0.5	2.7	5.0	0.5	6.5	
	OE	OE Y	2.7V	0.5	3.0	5.0	0.5	6.5	n
			3.3V ± 0.3V	0.5	3.1	5.0	0.5	6.5	7
			5.0V ± 0.5V	0.5	2.2	4.2	0.5	5.5	

Operating Characteristics

T _A = +25°	°C							
Devenuerten		Test	V _{CC} = 1.8V	$V_{CC} = 2.5V$	$V_{CC} = 3.3V$	$V_{CC} = 5V$	Unit	
	Parameter		Conditions	Тур	Тур	Тур	Тур	Unit
0	Power Dissipation	Outputs Enabled	f 10MU-	19	19	19	21	~
Cpd	C _{pd} Capacitance	Outputs Disabled	f = 10MHz	2	2	3	4	рF



Parameter Measurement Information

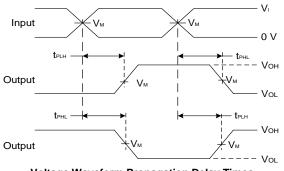


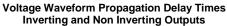
TEST	S1
t _{PLH} /t _{PHL}	Open
t _{PLZ} /t _{PZL}	V _{LOAD}
t _{PHZ} /t _{PZH}	GND

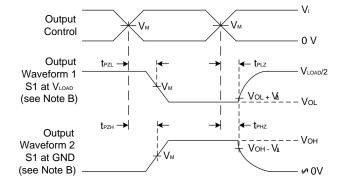
V	Inputs		N	V	6		VA
V _{cc}	VI	t _r /t _f	V _M	V _{LOAD}	C∟	RL	VA
1.8V±0.15V	Vcc	≤2ns	V _{CC} /2	2 x V _{CC}	30pF	1kΩ	0.15V
2.5V±0.2V	Vcc	≤2ns	V _{CC} /2	2 x V _{CC}	30pF	500Ω	0.15V
2.7V	2.7V	≤2.5ns	1.5V	6V	50pF	500Ω	0.3V
3.3V±0.3V	3V	≤2.5ns	1.5V	6V	50pF	500Ω	0.3V
5V±0.5V	V _{CC}	≤2.5ns	V _{CC} /2	$2 \times V_{CC}$	50pF	500Ω	0.3V



Voltage Waveform Pulse Duration







Voltage Waveform Enable and Disable Times Low and High Level Enabling

Figure 1 Load Circuit and Voltage Waveforms

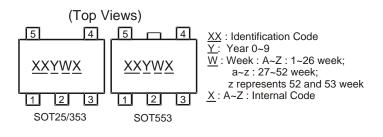
Notes: A. Includes test lead and test apparatus capacitance.

- B. All pulses are supplied at pulse repetition rate \leq 10MHz.
- C. Inputs are measured separately one transition per measurement.
- D. tPLz and tPHz are the same as $t_{dis.}$
- E. tPZL and tPZH are the same as tEN
- F. tPLH and tPHL are the same as tPD.



Marking Information

(1) SOT25, SOT353 and SOT553



Part Number	Package	Identification Code
74LVC1G125W5-7	SOT25	UY
74LVC1G125SE-7	SOT353	UY
74LVC1G125Z-7	SOT553	UY

(2) DFN Packages

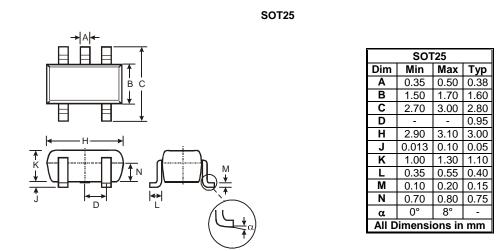


 $\begin{array}{l} \underline{XX}: \text{Identification Code} \\ \underline{Y}: \text{ Year } 0 \text{--} 9 \\ \underline{W}: \text{Week}: \text{A--} \text{Z}: 1 \text{--} 26 \text{ week}; \\ \text{a--} \text{z}: 27 \text{--} 52 \text{ week}; \\ \text{z represents } 52 \text{ and } 53 \text{ week} \\ \underline{X}: \text{A--} \text{Z}: \text{Internal Code} \end{array}$

	Part Number	Package	Identification Code
7	4LVC1G125FS3-7	X2-DFN0808-4	WY
7	4LVC1G125FW5-7	X1-DFN1010-6 (Type B)	VY
7	4LVC1G125FW4-7	X2-DFN1010-6	UY
7	4LVC1G125FX4-7	X2-DFN1409-6	MW
7	4LVC1G125FZ4-7	X2-DFN1410-6	UY

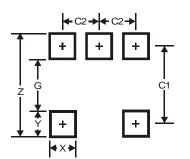


Please see http://www.diodes.com/package-outlines.html for the latest version.



Suggested Pad Layout

Please see http://www.diodes.com/package-outlines.html for the latest version.

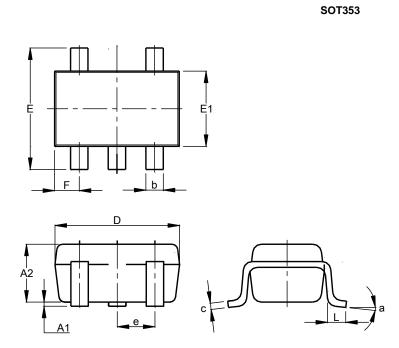


SOT25

Dimensions	Value
Z	3.20
G	1.60
Х	0.55
Y	0.80
C1	2.40
C2	0.95



Please see http://www.diodes.com/package-outlines.html for the latest version.

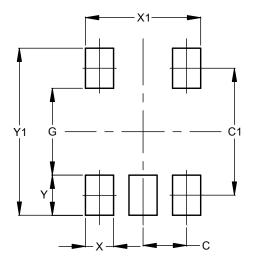


SOT353						
Dim	Min	Min Max Typ				
A1	0.00	0.10	0.05			
A2	0.90	1.00	1.00			
b	0.10	0.30	0.25			
c	0.10	0.22	0.11			
D	1.80	2.20	2.15			
ш	2.00	2.20	2.10			
E1	1.15	1.35	1.30			
е	C).650 B	SC			
F	0.40	0.45	0.425			
L	0.25	0.40	0.30			
а	0°	8°				
All Dimensions in mm						

Suggested Pad Layout

Please see http://www.diodes.com/package-outlines.html for the latest version.

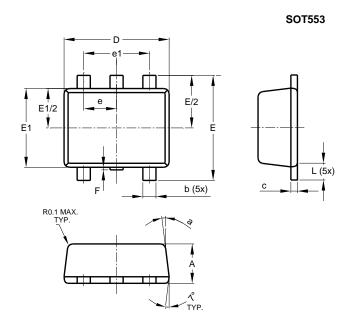
SOT353



Dimensions	Value (in mm)	
С	0.650	
C1	1.900	
G	1.300	
Х	0.420	
X1	1.720	
Y	0.600	
Y1	2.500	



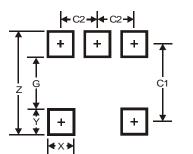
Please see http://www.diodes.com/package-outlines.html for the latest version.



	SOT553				
Dim	Min	Max	Тур		
Α	0.55	0.62	0.60		
b	0.15	0.30	0.20		
С	0.10	0.18	0.15		
D	1.50	1.70	1.60		
Е	1.55	1.70	1.60		
E1	1.10	1.25	1.20		
е	0.50 BSC				
e1	1.	00 BS(С		
F	0.00	0.10			
L	0.10	0.30	0.20		
а	6°	8°	7°		
All Di	All Dimensions in mm				

Suggested Pad Layout

Please see http://www.diodes.com/package-outlines.html for the latest version.



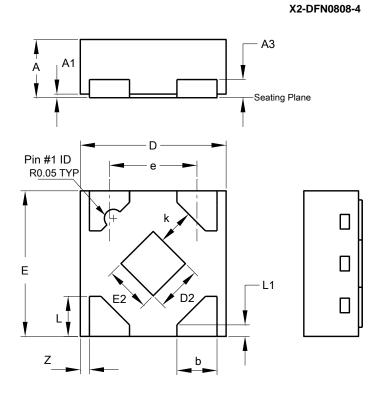
SOT553

Dimensions	Value
Z	2.2
G	1.2
Х	0.375
Y	0.5
C1	1.7
C2	0.5

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Please see http://www.diodes.com/package-outlines.html for the latest version.

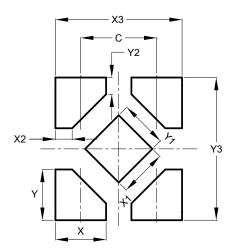


X2-DFN0808-4					
Dim	Min Max Typ				
Α	0.25	0.35	0.30		
A1	0	0.04	0.02		
A3	-	-	0.13		
b	0.17	0.27	0.22		
D	0.75	0.85	0.80		
D2	0.15	0.35	0.25		
Е	0.75	0.85	0.80		
E2	0.15	0.35	0.25		
е	-	-	0.48		
k	0.20	-	-		
L	0.17	0.27	0.22		
L1	0.02	0.12	0.07		
z	-	-	0.05		
A	All Dimensions in mm				

Suggested Pad Layout

Please see http://www.diodes.com/package-outlines.html for the latest version.

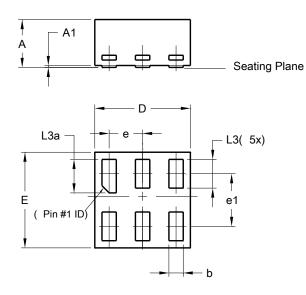
X2-DFN0808-4



Dimensions	Value
С	0.480
Х	0.320
X1	0.300
X2	0.106
Х3	0.800
Y	0.320
Y1	0.300
Y2	0.106
Y3	0.900



Please see http://www.diodes.com/package-outlines.html for the latest version.



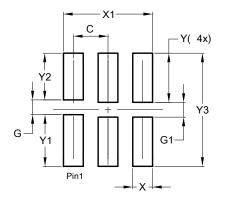
	X1-DFN1010-6				
	(Type B)				
Dim	Min Max Typ				
Α	-	0.50	0.39		
A1	-	0.04	-		
b	0.12	0.20	0.15		
D	0.95	1.050	1.00		
Е	0.95	1.050	1.00		
e 0.35 BSC					
e1		0.55 B	SC		
L3	0.27	0.30	0.30		
L3a	0.32	0.40	0.35		
All	All Dimensions in mm				

Suggested Pad Layout

Please see http://www.diodes.com/package-outlines.html for the latest version.

X1-DFN1010-6 (Type B)

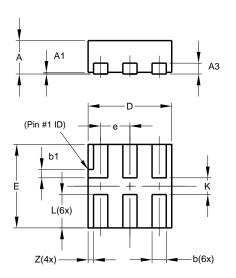
X1-DFN1010-6 (Type B)



Dimensions	Value
Dimensions	(in mm)
С	0.350
G	0.150
G1	0.150
Х	0.200
X1	0.900
Y	0.500
Y1	0.525
Y2	0.475
Y3	1.150



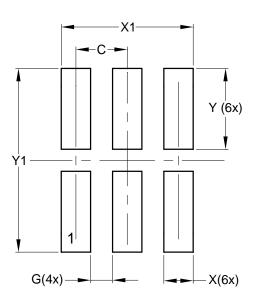
Please see http://www.diodes.com/package-outlines.html for the latest version.



	X2-DFN1010-6				
Dim	Min	Max	Тур		
Α		0.40	0.39		
A1	0.00	0.05	0.02		
A3			0.13		
b	0.14	0.20	0.17		
b1	0.05	0.15	0.10		
D	0.95	1.05	1.00		
E	0.95	1.05	1.00		
е	_	-	0.35		
L	0.35	0.45	0.40		
K	0.15				
Z	_		0.065		
All	All Dimensions in mm				

Suggested Pad Layout

Please see http://www.diodes.com/package-outlines.html for the latest version.



X2-DFN1010-6

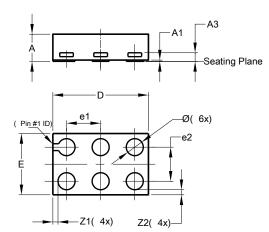
X2-DFN1010-6

Dimensions	Value (in mm)
С	0.350
G	0.150
Х	0.200
X1	0.900
Y	0.550
Y1	1.250



Please see http://www.diodes.com/package-outlines.html for the latest version.

X2-DFN1409-6 CHIP SCALE ALTERNATIVE

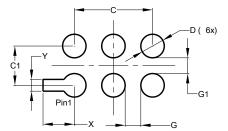


X2-DFN1409-6				
Dim	Min	Max	Тур	
Α	-	0.40	0.39	
A1	0	0.05	0.02	
A3	-	-	0.13	
Ø	0.20	0.30	0.25	
D	1.35	1.45	1.40	
ш	0.85	0.95	0.90	
e1	-	-	0.50	
e2	-	-	0.50	
Z1	-	-	0.075	
Z2	-	-	0.075	
All Dimensions in mm				

Suggested Pad Layout

Please see http://www.diodes.com/package-outlines.html for the latest version.

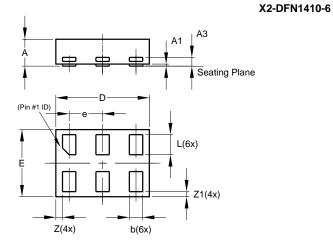
X2-DFN1409-6 CHIP SCALE ALTERNATIVE



Dimensions	Value	
	(in mm)	
C	1.000	
C1	0.500	
D	0.300	
G	0.200	
G1	0.200	
Х	0.400	
Y	0.150	



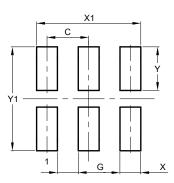
Please see http://www.diodes.com/package-outlines.html for the latest version.



X2-DFN1410-6					
Dim	Min	Max	Тур		
Α	-	0.40	0.39		
A1	0.00	0.05	0.02		
A3		_	0.13		
b	0.15	0.25	0.20		
D	1.35	1.45	1.40		
E	0.95	1.05	1.00		
e			0.50		
L	0.25	0.35	0.30		
Z			0.10		
Z1	0.045	0.105	0.075		
All Dimensions in mm					

Suggested Pad Layout

Please see http://www.diodes.com/package-outlines.html for the latest version.



X2-DFN1410-6

Dimensions	Value (in mm)
С	0.500
G	0.250
X	0.250
X1	1.250
Y	0.525
Y1	1.250



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